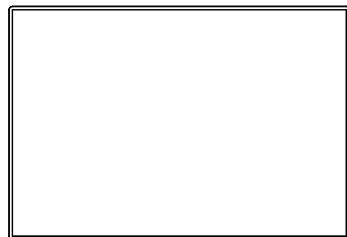
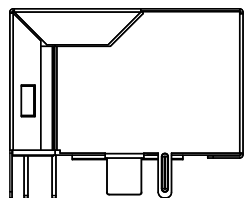


REACH & RoHS  
COMPLIANT

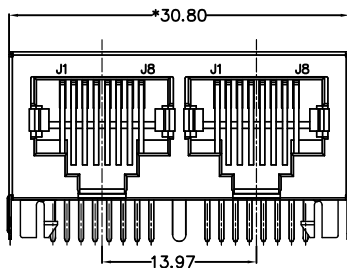
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.12.29



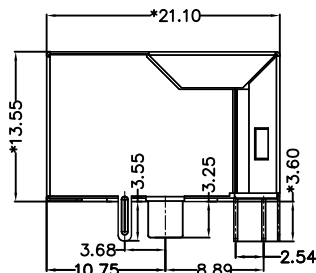
TOP VIEW



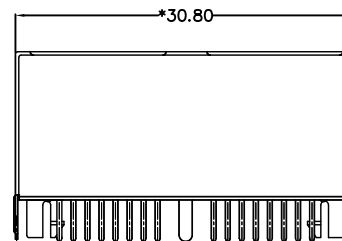
LEFT SIDE VIEW



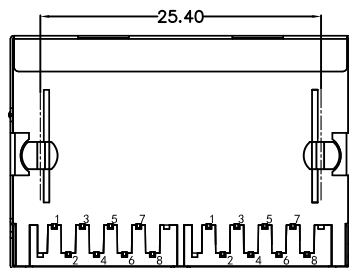
FRONT VIEW



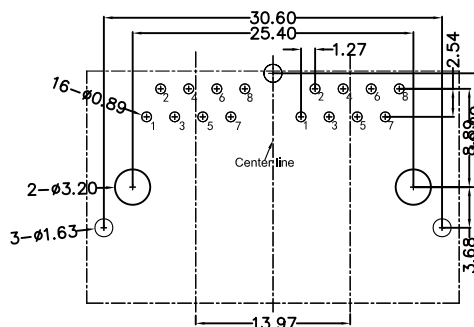
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT  
VIEWED FROM COMPONENT SIDE

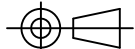
**MATERIAL:**

HOUSING: PBT,UL94V-0,BLACK.  
TERMINALS BRACKET: PBT,UL94V-0,BLACK.  
SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.  
TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,  
6U" GOLD PLATING ON CONTACT AREA.

**MECHANICAL:**

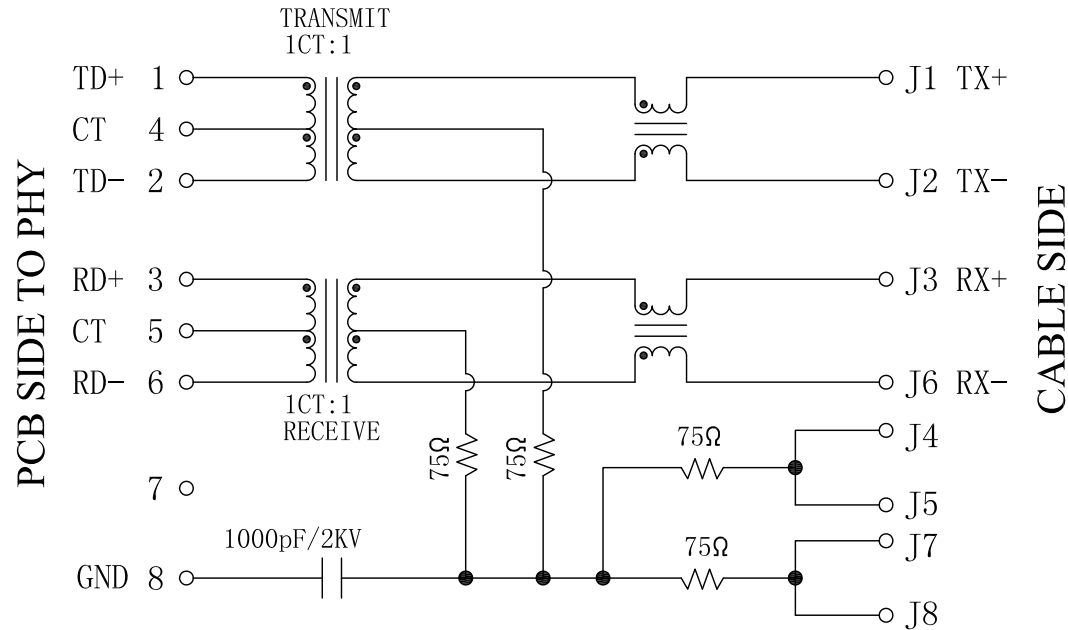
DURABILITY: 750 CYCLES MIN.  
MATING FORCE: 30N MAX.  
OPERATING TEMPERATURE: -40°C~+85°C.  
STORAGE TEMPERATURE: -40°C~+85°C.  
ALL CRITICAL DIMENSIONS WITH "\*"

 东莞市浚程电子科技有限公司  
DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD

TITLE: TAB-DOWN 1X2 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: FCRJ-112B002GWA1D5	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/3		.x±0.30	.x°±2.0°	DESIGND BY: MQ.Qu
			.xx±0.25	.xx°±1.5°	
			.xxx±0.10	.xxx°±1.0°	

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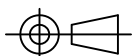
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.12.29



**Electrical:**

1. Turn ratio: 1~2: J1~J2=1CT:1CT(±2%).  
3~6: J3~J6=1CT:1CT(±2%).
2. OCL: 350uH Min. at 100KHz 100mV 8mA DC.
3. Insertion Loss: -1.0 dB Max 1~100MHz.
4. Return loss: -20dB Min 1~10MHz;  
-16dB Min 10~30MHz.  
-12dB Min 30~60MHz.  
-10dB Min 60~80MHz.
5. Cross talk: -40dB Min 1~30MHz;  
-35dB Min 30~60MHz;  
-30dB Min 60~100MHz;
6. CMR: -35dB Min 1~100MHz;
7. Hi-Pot: 1500V AC & 2250V DC  
6S 1mA PRI TO SEC

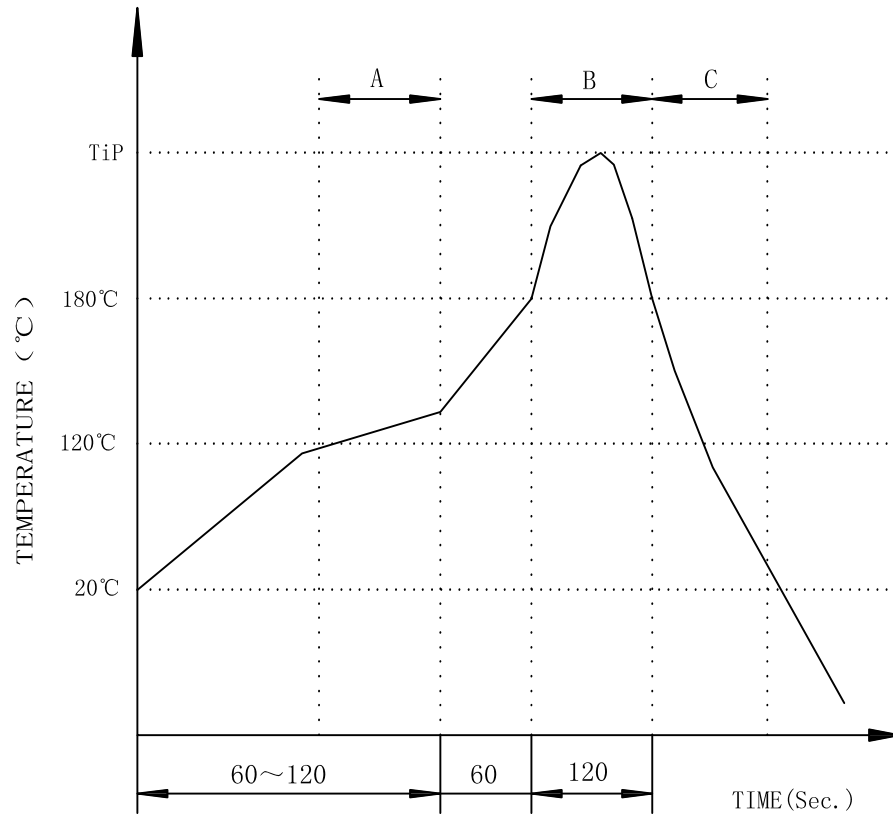
 东莞市涪程电子科技有限公司  
DONG GUAN FU CHENG ELECTRONIC TECHNOLOGY Co., LTD

TITLE: TAB-DOWN 1X2 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: FCRJ-112B002GWA1D5	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 2/3		.xx±0.25	.xx°±1.5°	DESIGND BY: MQ.Qu
			.xxx±0.10	.xxx°±1.0°	

REACH & RoHS  
COMPLIANT

# PROFILE OF WAVE SOLDER

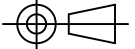
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.12.29



A.Preheating B.Soldering C.Gradual Cooling  
 Tip temperature:260±5°C.  
 Tip temperature time:5Sec Max.  
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

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TITLE: TAB-DOWN 1X2 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: FCRJ-112B002GWA1D5	SACLE 1:1	REV A0	$x \pm 0.35$	$x^\circ \pm 3.0^\circ$	CHECKED BY: TW.Xu
REMARK:	SHEET 3/3		$.xx \pm 0.25$	$.xx^\circ \pm 1.5^\circ$	DESIGND BY: MQ.Qu
			$.xxx \pm 0.10$	$.xxx^\circ \pm 1.0^\circ$	